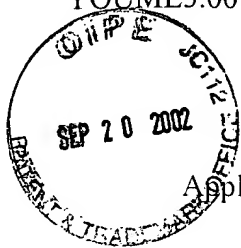


## PATENT



#5/B  
9/26/02  
JC

Applicant : Ko, et al.

Appl. No. : 09/776,383

Filed : 02/02/2001

For : SEMICONDUCTOR  
INTERLAYER DIELECTRIC  
MATERIAL AND A  
SEMICONDUCTOR DEVICE  
USING THE SAME

Examiner : Zimmer, M. S.

Group Art Unit 1712

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

September 16, 2002

(Date)

Rose M. Thiessen, Reg. No. 40,202

336.00 OP

## AMENDMENT

01 FC:102

United States Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

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SEP 25 2002

TC 1700

Dear Sir:

In response to the Office Action mailed March 14, 2002, Applicants respectfully request that the Examiner enter the following amendments and consider the following remarks.

IN THE CLAIMS:

**Please cancel claims 1-3, 5, and 6.**

**Please amend Claims 4 and 7-11 as follows:**

4. (Amended) A process for preparing an organic silicate polymer having a flexible bridge unit in the network comprising the step of:

reacting the following component (a) with the following component (b) in an organic solvent after addition of water and catalyst:

(a) organosilane of the formula  $R^1_m R^2_n SiX_{4-m-n}$  (where each of  $R^1$  and  $R^2$  which may be the same or different, is a non-hydrolysable group selected from hydrogen, alkyl, fluorine-containing alkyl or aryl group; X is a hydrolysable group selected from halide, alkoxy or